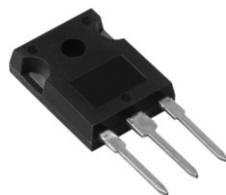
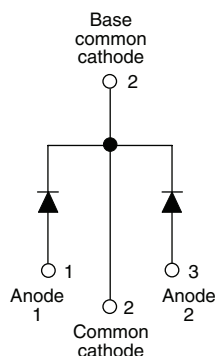


HEXFRED® Ultrafast Soft Recovery Diode, 2 x 8 A



TO-247AC



FEATURES

- Ultrafast recovery
- Ultrasoft recovery
- Very low I_{RRM}
- Very low Q_{rr}
- Specified at operating conditions
- Designed and qualified for industrial level

BENEFITS

- Reduced RFI and EMI
- Reduced power loss in diode and switching transistor
- Higher frequency operation
- Reduced snubbing
- Reduced parts count

DESCRIPTION

HFA16PA120C is a state of the art ultrafast recovery diode. Employing the latest in epitaxial construction and advanced processing techniques it features a superb combination of characteristics which result in performance which is unsurpassed by any rectifier previously available. With basic ratings of 1200 V and 8 A per leg continuous current, the HFA16PA120C is especially well suited for use as the companion diode for IGBTs and MOSFETs. In addition to ultrafast recovery time, the HEXFRED® product line features extremely low values of peak recovery current (I_{RRM}) and does not exhibit any tendency to “snap-off” during the t_b portion of recovery. The HEXFRED features combine to offer designers a rectifier with lower noise and significantly lower switching losses in both the diode and the switching transistor. These HEXFRED advantages can help to significantly reduce snubbing, component count and heatsink sizes. The HEXFRED HFA16PA120C is ideally suited for applications in power supplies and power conversion systems (such as inverters), motor drives, and many other similar applications where high speed, high efficiency is needed.

PRODUCT SUMMARY

V_R per leg	1200 V
V_F at 8 A at 25 °C	3.3 V
$I_{F(AV)}$	2 x 8 A
t_{rr} (typical)	28 ns
T_J (maximum)	150 °C
I_{RRM} (typical) per leg	4.5 A

ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Cathode to anode voltage	V_R		1200	V
Maximum continuous forward current per leg per device	I_F	$T_C = 100\text{ °C}$	8	A
			16	
			130	
			32	
Single pulse forward current	I_{FSM}		130	
Maximum repetitive forward current	I_{FRM}		32	
Maximum power dissipation	P_D	$T_C = 25\text{ °C}$	73.5	W
		$T_C = 100\text{ °C}$	29	
Operating junction and storage temperature range	T_J, T_{Stg}		- 55 to + 150	°C

ELECTRICAL SPECIFICATIONS PER LEG ($T_J = 25\text{ }^{\circ}\text{C}$ unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Cathode to anode breakdown voltage	V_{BR}	$I_R = 100\text{ }\mu\text{A}$	1200	-	-	V
Maximum forward voltage	V_{FM}	$I_F = 8.0\text{ A}$	-	2.6	3.3	
		$I_F = 16\text{ A}$	-	3.4	4.3	
		$I_F = 8.0\text{ A}, T_J = 125\text{ }^{\circ}\text{C}$	-	2.4	3.1	
Maximum reverse leakage current	I_{RM}	$V_R = V_R\text{ rated}$	-	0.31	10	μA
		$T_J = 125\text{ }^{\circ}\text{C}, V_R = 0.8 \times V_R\text{ rated}$	-	135	1000	
Junction capacitance	C_T	$V_R = 200\text{ V}$	-	11	20	pF
Series inductance	L_S	Measured lead to lead 5 mm from package	-	8.0	-	nH

DYNAMIC RECOVERY CHARACTERISTICS PER LEG ($T_J = 25\text{ }^{\circ}\text{C}$ unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Reverse recovery time	t_{rr}	$I_F = 1.0\text{ A}, dI_F/dt = 200\text{ A}/\mu\text{s}, V_R = 30\text{ V}$	-	28	-	ns
	t_{rr1}	$T_J = 25\text{ }^{\circ}\text{C}$	-	63	95	
	t_{rr2}	$T_J = 125\text{ }^{\circ}\text{C}$	-	106	160	
Peak recovery current	I_{RRM1}	$T_J = 25\text{ }^{\circ}\text{C}$	-	4.5	8.0	A
	I_{RRM2}	$T_J = 125\text{ }^{\circ}\text{C}$	-	6.2	11	
Reverse recovery charge	Q_{rr1}	$T_J = 25\text{ }^{\circ}\text{C}$	-	140	380	nC
	Q_{rr2}	$T_J = 125\text{ }^{\circ}\text{C}$	-	335	880	
Peak rate of recovery current during t_b	$dI_{(rec)M}/dt1$	$T_J = 25\text{ }^{\circ}\text{C}$	-	133	-	A/ μs
	$dI_{(rec)M}/dt2$	$T_J = 125\text{ }^{\circ}\text{C}$	-	85	-	

THERMAL - MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Lead temperature	T_{lead}	0.063" from case (1.6 mm) for 10 s	-	-	300	$^{\circ}\text{C}$
Thermal resistance, junction to case	R_{thJC}		-	-	1.7	K/W
Thermal resistance, junction to ambient	R_{thJA}	Typical socket mount	-	-	40	
Thermal resistance, case to heatsink	R_{thCS}	Mounting surface, flat, smooth and greased	-	0.25	-	
Weight			-	6.0	-	g
			-	0.21	-	oz.
Mounting torque			6.0 (5.0)	-	12 (10)	kgf · cm (lbf · in)
Marking device		Case style TO-247AC (JEDEC)	HFA16PA120C			

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Vishay High Power Products

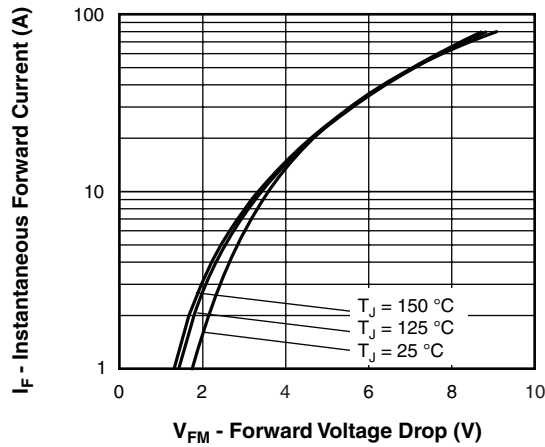


Fig. 1 - Maximum Forward Voltage Drop Characteristics

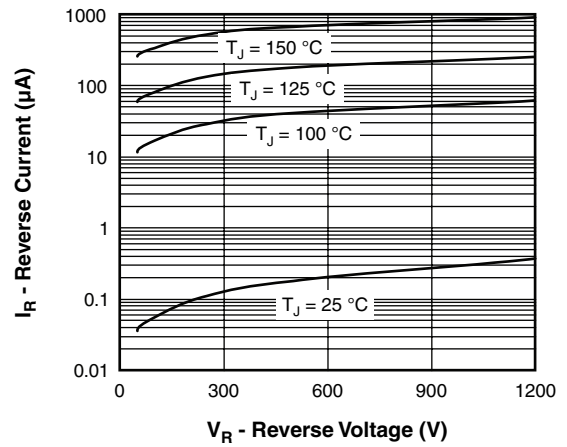


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

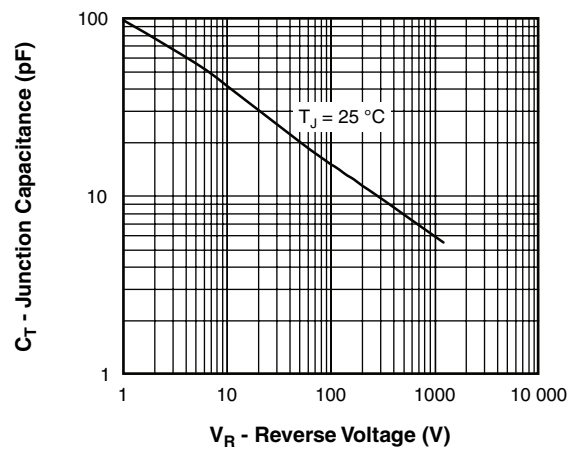


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

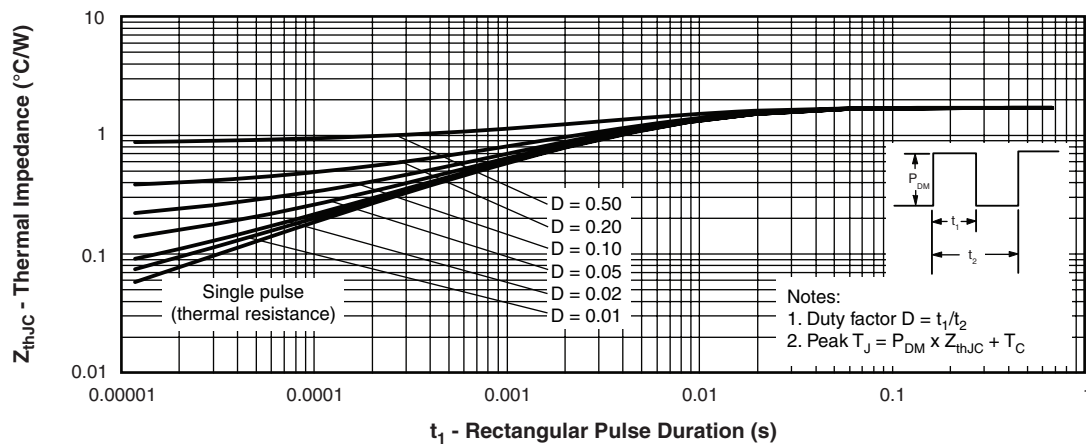


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics

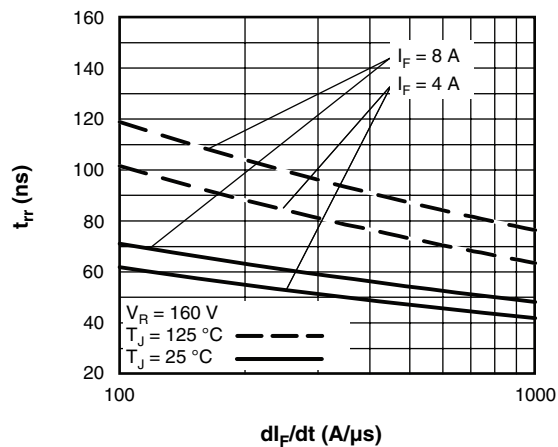


Fig. 5 - Typical Reverse Recovery Time vs. dI_F/dt

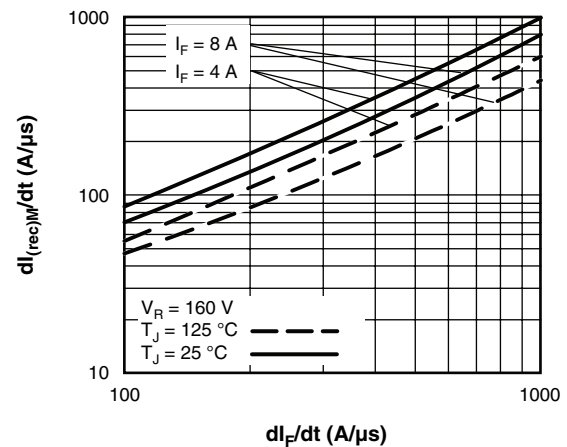


Fig. 7 - Typical Stored Charge vs. dI_F/dt

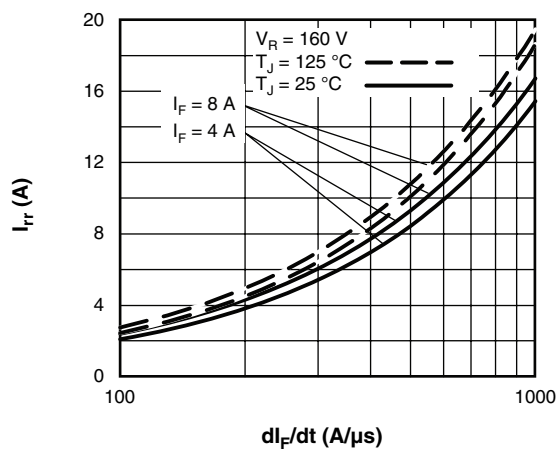


Fig. 6 - Typical Recovery Current vs. dI_F/dt

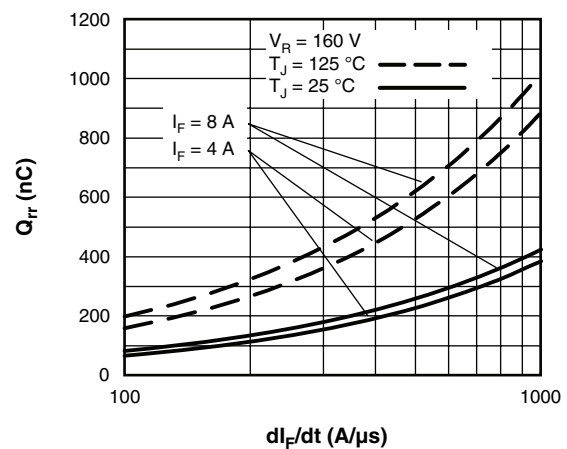


Fig. 8 - Typical $dI_{(rec)M}/dt$ vs. dI_F/dt

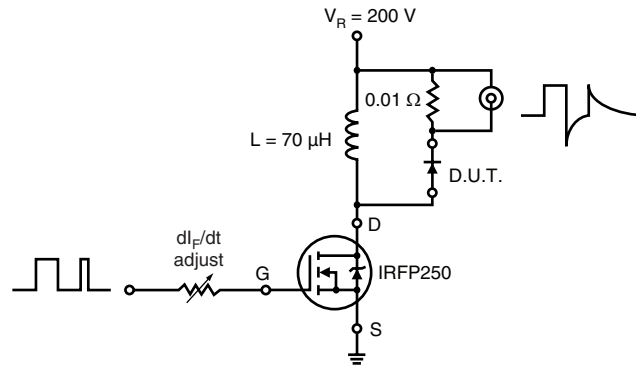


Fig. 9 - Reverse Recovery Parameter Test Circuit

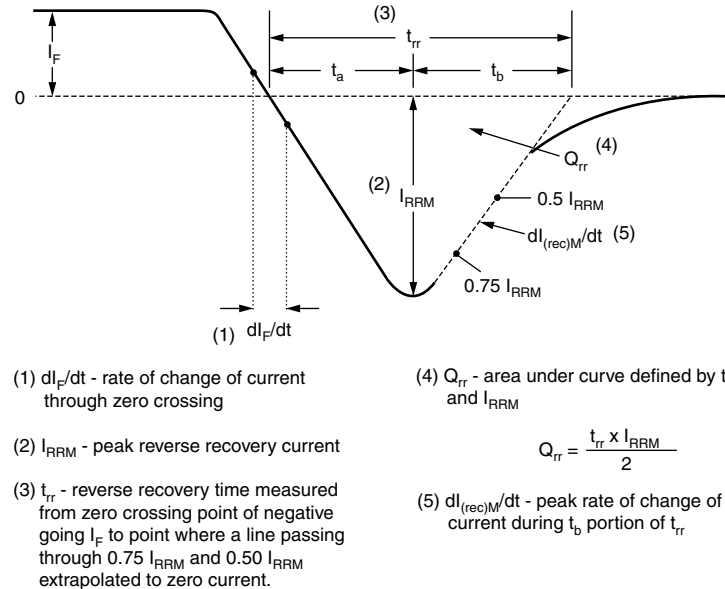


Fig. 10 - Reverse Recovery Waveform and Definitions

ORDERING INFORMATION TABLE

Device code	HF	A	16	PA	120	C	-
	1	2	3	4	5	6	7
1	- HEXFRED® family						
2	- Process designator: A = Subs. electron irradiated B = Subs. platinum						
3	- Current rating (16 = 16 A)						
4	- Package outline (PA = TO-247, 3 pins)						
5	- Voltage rating (120 = 1200 V)						
6	- Configuration (C = Center tap common cathode)						
7	- • None = Standard production • PbF = Lead (Pb)-free						

LINKS TO RELATED DOCUMENTS	
Dimensions	http://www.vishay.com/doc?95223
Part marking information	http://www.vishay.com/doc?95226



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